

OKI semiconductor 7-46-23-17

MSC2329-xxYS3/KS3 O K I SEMICONDUCTOR GROUP

262,144 Word BY 9 Bit DYNAMIC RAM MODULE : PAGE MODE TYPE

GENERAL DESCRIPTION

The Oki MSC2329-xxYS3/KS3 is a fully decoded, 262,144 word \times 9 bit dynamic random access memory composed of two 1 Mb DRAMs in SOJ (MSM514256AJS) and one 256Kb DRAM in PLCC (MSM41256AJS). The mounting of two SOJs and one PLCC together with three 0.2 μ F decoupling capacitors on a 30 pin glass epoxy Single-In-Line Package supports any application where high density and large capacity of storage memory are required. The electrical characteristics of the MSC2329-xxYS3/KS3 are same as the original MSM41256AJS; each timing requirements are noncritical, and power supply tolerance is very wide.

FEATURES

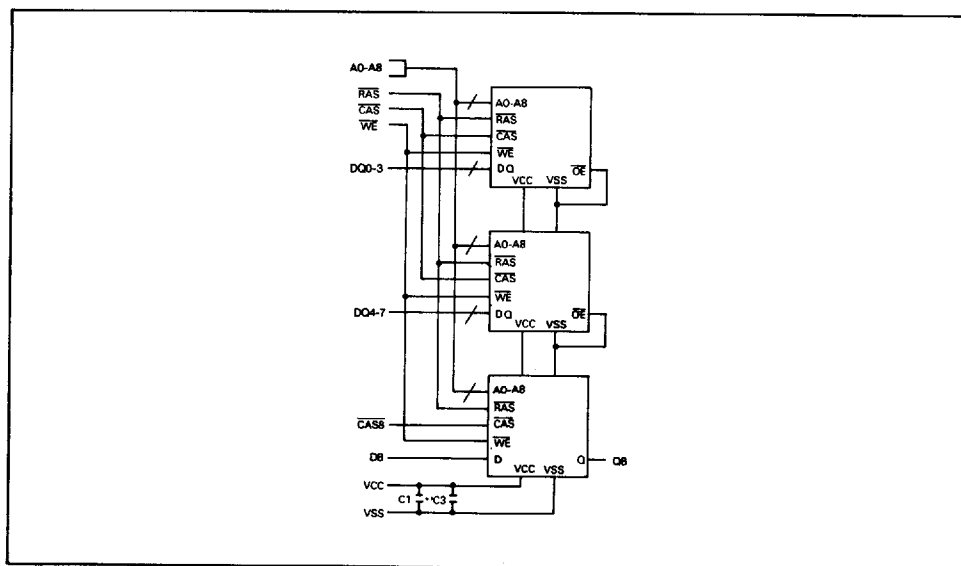
- 262,144 word \times 9 bit organization
- 30-Pin Socket Insertable Module
- Family organization

Family	Access Time (MAX)		Cycle Time (MIN)	Power Dissipation	
	t _{RAC}	t _{CAC}		Operating (MAX)	Standby (MAX)
MSC2329-10YS3/KS3	100ns	50ns	200ns	1155mW	50mW
MSC2329-12YS3/KS3	120ns	60ns	220ns	1073mW	

- Single + 5V supply, $\pm 10\%$ tolerance
- Input : TTL compatible
- Output : TTL compatible, tristate, nonlatch
- Refresh : 512 cycles/8 ms
- Common CAS Control for eight Common Data-in and Data-Out Lines
- Separate CAS Control for One Separate Pair of Data-in and Data-Out Lines

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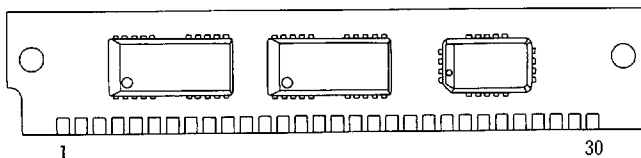
FUNCTIONAL BLOCK DIAGRAM



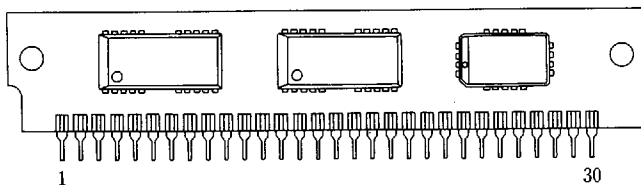
PIN CONFIGURATION

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MS2329-xxYS3



MS2329-xxKS3



PIN No.	PIN NAME	PIN No.	PIN NAME	PIN No.	PIN NAME
1	Vcc	11	A4	21	WE
2	CAS	12	A5	22	VSS
3	DQ0	13	DQ3	23	DQ6
4	A0	14	A6	24	NC
5	A1	15	A7	25	DQ7
6	DQ1	16	DQ4	26	Q8
7	A2	17	A8	27	RAS
8	A3	18	NC	28	CASB
9	VSS	19	NC	29	D8
10	DQ2	20	DQ5	30	Vcc

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Voltage on any pin relative to VSS	V _{IN} , V _{OUT}	-1 ~ +7	V
Voltage on V _{CC} supply relative to VSS	V _{CC}	-1 ~ +7	V
Operating temperature	T _{opr}	0 ~ 70	°C
Storage temperature	T _{stg}	-40 ~ +125	°C
Power dissipation	P _D	4	W
Short circuit output current	I _{OS}	50	mA

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Referenced to V_{SS})

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Parameter	Symbol	Min.	Typ.	Max.	Unit	Operating temperature
Supply Voltage	V_{CC}	4.5	5.0	5.5	V	0°C ~ +70°C
	V_{SS}	0	0	0	V	
Input High Voltage, all inputs	V_{IH}	2.4	—	6.5	V	
Input Low Voltage, all inputs	V_{IL}	-1.0	—	0.8	V	

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DC CHARACTERISTICS

($V_{CC}=5V \pm 10\%$, $T_a=0 \sim +70^\circ C$)

Parameter	Symbol	Condition	MSC2329-10YS3/KS3		MSC2329-12YS3/KS3		Unit	Note
			Min.	Max.	Min.	Max.		
Input Leakage Current	I_{LI}	$0V \leq V_{IN} \leq 6.5V$: All other pins not under test = 0V	-30	30	-30	30	μA	
Output Leakage Current	I_{LO}	DQ0-7, Q8 = disable $0V \leq V_{OUT} \leq 5.5V$	-10	10	-10	10	μA	
Output high voltage	V_{OH}	$I_{OH} = -5.0mA$	2.4	—	2.4	—	V	
Output low voltage	V_{OL}	$I_{OL} = 4.2mA$	—	0.4	—	0.4	V	
Average power supply current (Operating)	I_{CC1}	\overline{RAS} , \overline{CAS} , $\overline{CAS8}$ cycling, $t_{RC} = \text{min}$	—	210	—	195	mA	1, 2
Power supply current (Standby)	I_{CC2}	$\overline{RAS} = V_{IH}$ \overline{CAS} , $\overline{CAS8} = V_{IH}$	—	9	—	9	mA	
Average power supply current (RAS only refresh)	I_{CC3}	\overline{RAS} cycling, \overline{CAS} , $\overline{CAS8} = V_{IH}$ $t_{RC} = \text{min}$	—	205	—	190	mA	1, 2
Average power supply current (CAS before RAS refresh)	I_{CC6}	$t_{RC} = \text{min}$.	—	205	—	190	mA	1
Average power supply current (Fast page mode)	I_{CC7}	$\overline{RAS} = V_{IL}$ \overline{CAS} , $\overline{CAS8}$ cycling $t_{PC} = \text{min}$.	—	150	—	135	mA	1, 3

- Note : 1. I_{CC} in dependent on out put loading and cycle rates.
 Specified value are obtained with the output open.
 2. Address can be changed once or less while $\overline{RAS} = V_{IL}$.
 3. Address can be changed once or less while $\overline{CAS} = V_{IH}$.

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CAPACITANCE

(Ta = 25°C, f = 1 MHz)

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Parameter	Symbol	Max.	Unit
Input Capacitance (A0 — A8)	CIN1	40	pF
Input Capacitance ($\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WE}}$)	CIN2	40	pF
Data Input/Output Capacitance (DQ0 — DQ7)	CDQ	20	pF
Input Capacitance ($\overline{\text{CAS8}}$)	CIN3	10	pF
Input Capacitance (D8)	CIN4	10	pF
Output Capacitance (Q8)	COUT	15	pF

Capacitance measured with Boonton Meter.

AC CHARACTERISTICS

(VCC = 5V ± 10%, Ta = 0 ~ +70°C)

Note 1, 2, 3

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Parameter	Symbol	MS2329-10YS3/KS3		MS2329-12YS3/KS3		Unit	Note
		MIN	MAX	MIN	MAX		
Refresh period	tREF	—	4	—	4	ms	
Random read or write cycle time	tRC	200	—	220	—	ns	
Page mode cycle time	tPC	100	—	120	—	ns	
Access time from $\overline{\text{RAS}}$	tRAC	—	100	—	120	ns	4, 5
Access time from $\overline{\text{CAS}}$	tCAC	—	50	—	60	ns	4, 5
Output buffer turn-off delay	tOFF	0	30	0	30	ns	
Transition time	tT	3	50	3	50	ns	3
RAS precharge time	tRP	90	—	90	—	ns	
RAS pulse width	tRAS	100	10K	120	10K	ns	
RAS hold time	tRSH	50	—	60	—	ns	
CAS precharge time (Page mode cycle only)	tCP	40	—	50	—	ns	
CAS pulse width	tCAS	50	10K	60	10K	ns	
CAS hold time	tCSH	100	—	120	—	ns	
RAS to CAS delay time	tRCD	25	50	25	60	ns	5
CAS to RAS set-up time	tCRS	20	—	25	—	ns	
Row address set-up time	tASR	0	—	0	—	ns	
Row address hold time	tRAH	15	—	15	—	ns	
Column address set-up time	tASC	0	—	0	—	ns	
Column address hold time	tCAH	20	—	20	—	ns	
Column address hold time from $\overline{\text{RAS}}$	tAR	75	—	90	—	ns	

AC CHARACTERISTICS (Continued)

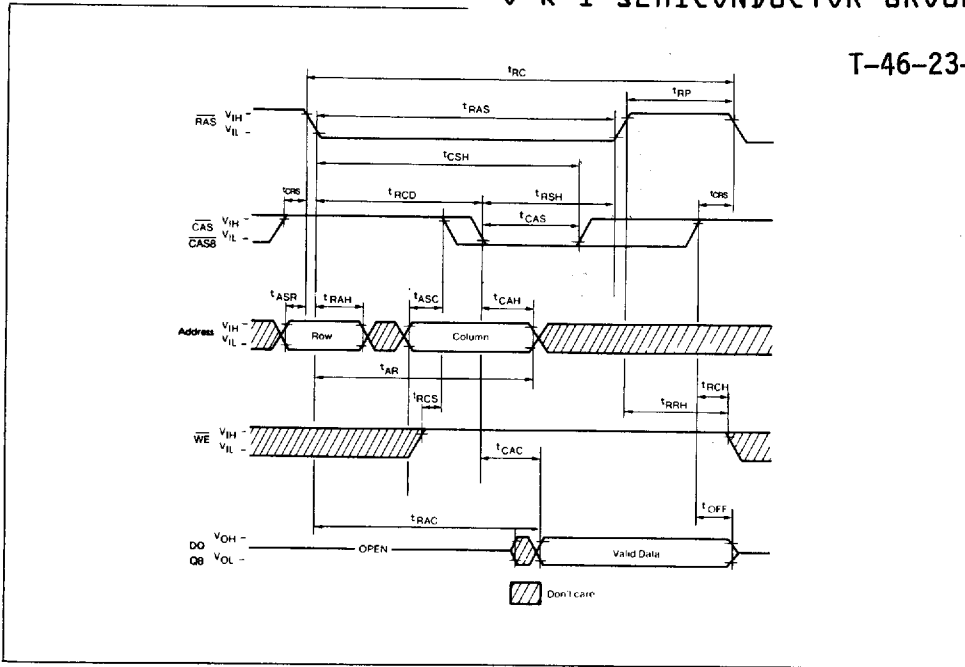
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Parameter	Symbol	MSC2329-10YS3/KS3		MSC2329-12YS3/KS3		Unit	Note
		MIN	MAX	MIN	MAX		
Read command set-up time	t _{RCS}	0	—	0	—	ns	
Read command hold time	t _{RCH}	0	—	0	—	ns	6
Write command hold time from $\overline{\text{RAS}}$	t _{WCR}	75	—	90	—	ns	
Write command set-up time	t _{WCS}	0	—	0	—	ns	
Write command hold time	t _{WCH}	20	—	20	—	ns	
Write command pulse width	t _{WP}	20	—	20	—	ns	
Date-in set-up time	t _{DS}	0	—	0	—	ns	
Data-in hold time	t _{DH}	20	—	20	—	ns	
Data-in hold time from $\overline{\text{RAS}}$	t _{DHR}	75	—	90	—	ns	
Read command hold time referenced to $\overline{\text{RAS}}$	t _{RRH}	20	—	20	—	ns	6
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ set-up time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$)	t _{FCS}	20	—	25	—	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ hold time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$)	t _{FCH}	20	—	25	—	ns	
$\overline{\text{CAS}}$ precharge time ($\overline{\text{CAS}}$ before $\overline{\text{RAS}}$)	t _{CPR}	20	—	25	—	ns	
$\overline{\text{CAS}}$ active delay from $\overline{\text{RAS}}$ precharge	t _{RPC}	20	—	20	—	ns	

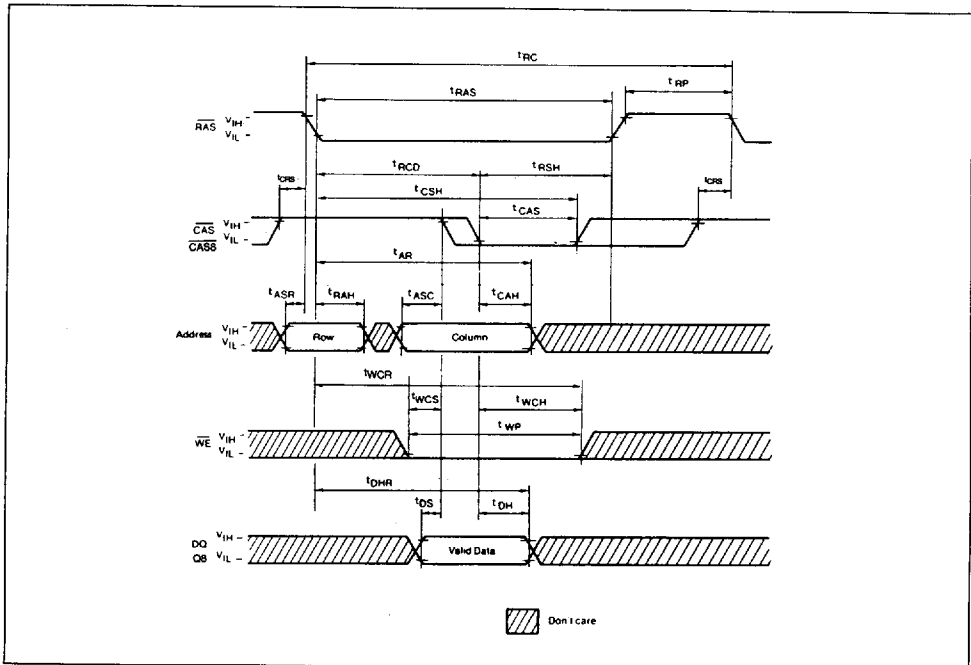
- Notes:**
- 1 An initial pause of 100 μs is required after power-up followed by any 8 $\overline{\text{RAS}}$ cycles (Example : $\overline{\text{RAS}}$ only refresh cycle) before proper device operation is achieved.
 - 2 The AC characteristics assume at $t_T = 5 \text{ ns}$.
 - 3 V_{IH} (min.) and V_{IL} (max.) are reference levels for measuring of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
 - 4 Measured with a load circuit equivalent to 2 TTL loads and 100pF
 - 5 Operation within the t_{RCD} (max.) limit insures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled exclusively by t_{CAC}.
 - 6 Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.

READ CYCLE

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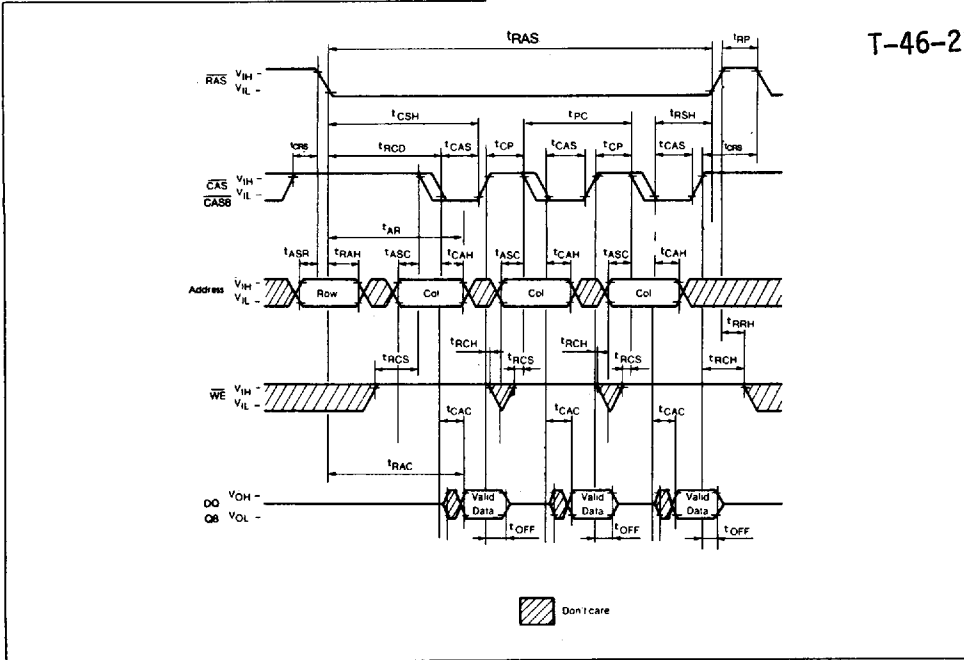
WRITE CYCLE (EARLY WRITE)



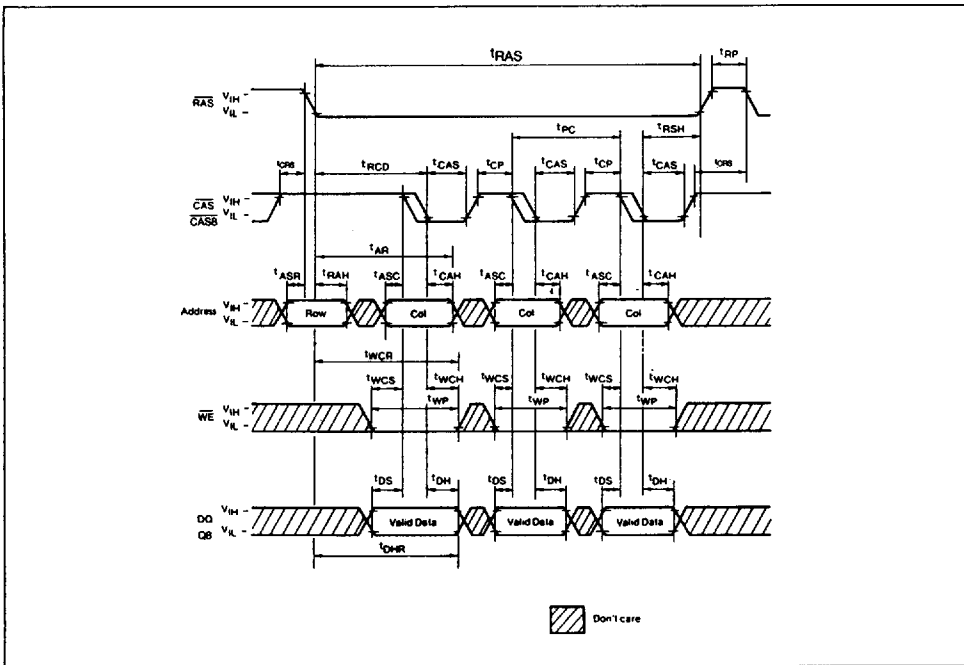
PAGE MODE READ CYCLE

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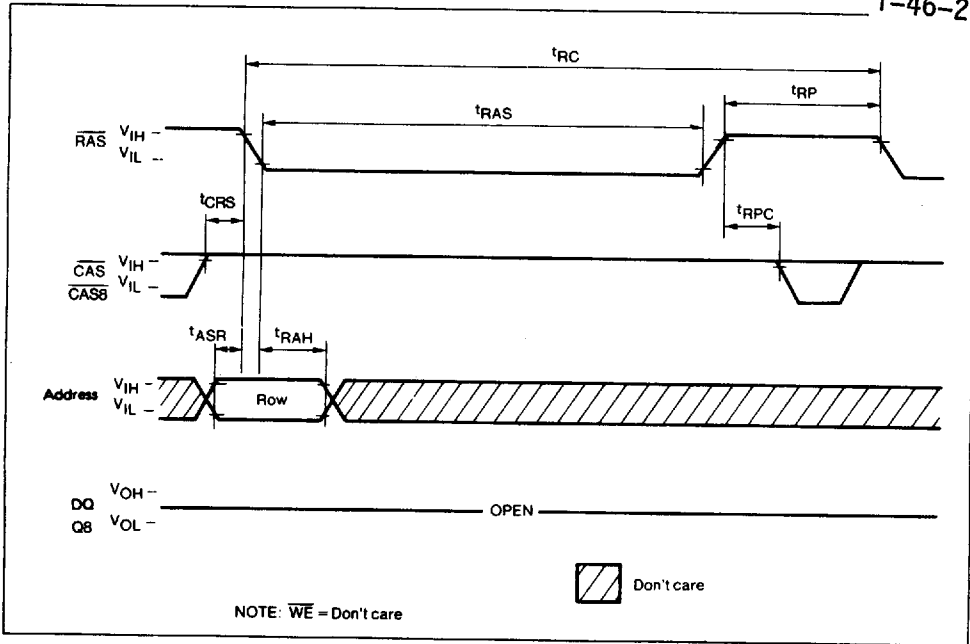


PAGE MODE CYCLE (EARLY WRITE)

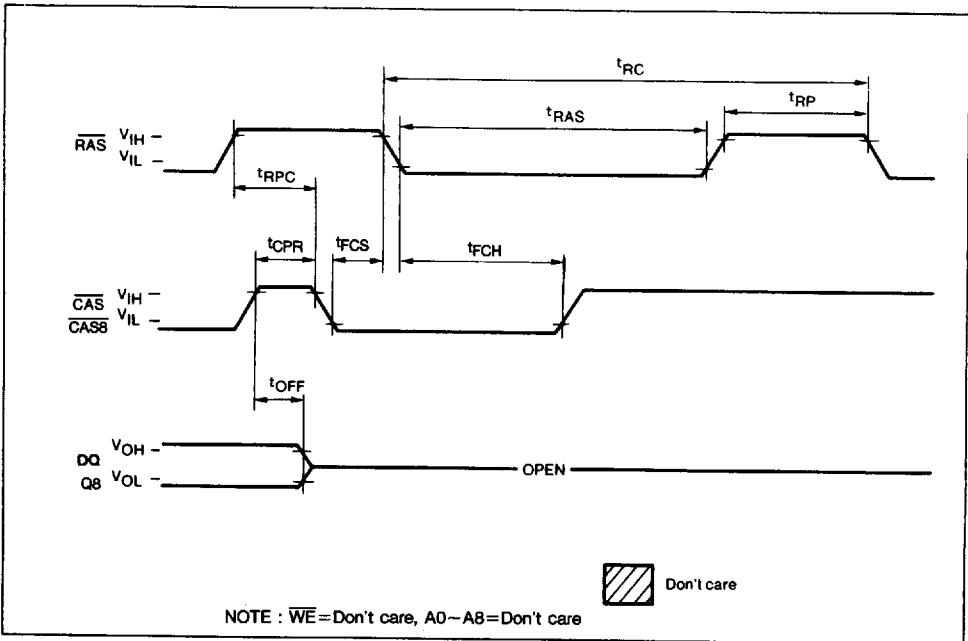


RAS ONLY REFRESH CYCLE

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CAS BEFORE RAS AUTO REFRESH CYCLE



HIDDEN REFRESH READ CYCLE

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